



## **ABSTRACT OF DISCLOSURE**

An object of the disclosure is to provide a vacuum processing apparatus capable of minimizing the size of the whole apparatus by reducing a floor area occupied by a vacuum pump. An etching apparatus 20 for applying an etching process on an object to be processed in a vacuum includes a processing vessel 21 for applying the etching process on a semiconductor wafer W introduced into the vessel 21 and a vacuum pump 30 arranged below the processing vessel 21 so as to be coaxial with the processing vessel 21, for sucking exhaust gas in the processing vessel 21 to form the vacuum.

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